Build in Biasing Circuit MOS FET IC UHF RF Amplifier

HITACHI

ADE-208-505 1st. Edition

Features

- Build in Biasing Circuit; To reduce using parts cost & PC board space.
- Low noise characteristics; (NF = 2.0 dB typ. at f = 900 MHz)
- Withstanding to ESD; Build in ESD absorbing diode. Withstand up to 200 V at C = 200 pF, Rs = 0 conditions.

Outline

CMPAK-4



- 1. Source
- 2. Gate1
- 3. Gate2
- 4. Drain



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

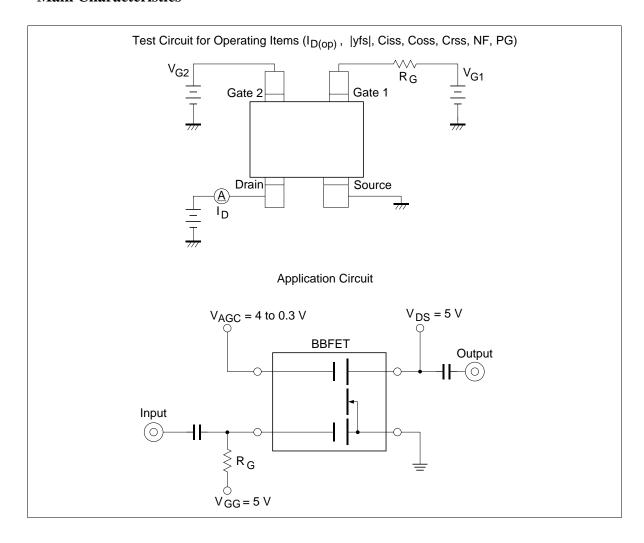
Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DS}	6	V	
Gate 1 to source voltage	V_{G1S}	+6 -0	V	
Gate 2 to source voltage	V_{G2S}	±6	V	
Drain current	I _D	25	mA	
Channel power dissipation	Pch	100	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

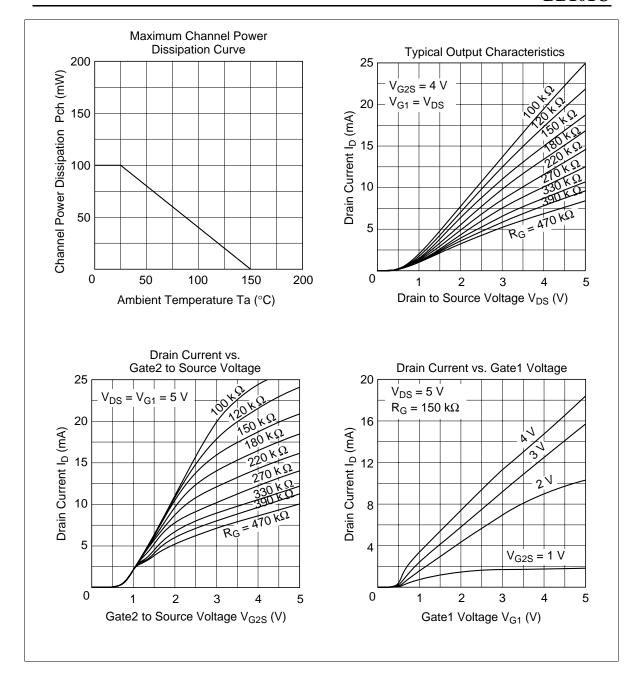
Electrical Characteristics ($Ta = 25^{\circ}C$)

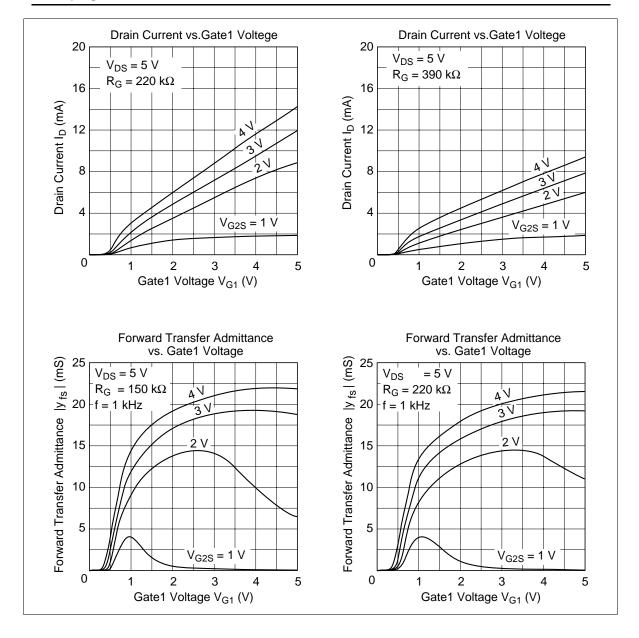
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source break down voltage	$V_{(BR)DSS}$	6	_	_	V	$I_D = 200 \mu A$ $V_{G1S} = V_{G2S} = 0$
Gate 1 to source breakdown voltage	$V_{(BR)G1SS}$	+6	_	_	V	$I_{G1} = +10 \mu A$ $V_{G2S} = V_{DS} = 0$
Gate 2 to source breakdown voltage	$V_{(BR)G2SS}$	±6	_	_	V	$I_{G2} = +10 \mu A$ $V_{G1S} = V_{DS} = 0$
Gate 1 to source cutoff current	I _{G1SS}	_	_	+100	nA	$V_{G1S} = +5 V$ $V_{G2S} = V_{DS} = 0$
Gate 2 to source cutoff current	I _{G2SS}	_	_	±100	nA	$V_{G2S} = \pm 5 V$ $V_{G1S} = V_{DS} = 0$
Gate 1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0.2	_	0.8	V	$V_{DS} = 5 \text{ V}, V_{G2S} = 4 \text{ V}$ $I_{D} = 100 \mu\text{A}$
Gate 2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0.4	_	1.0	V	$V_{DS} = 5 \text{ V}, V_{G1S} = 5 \text{ V}$ $I_{D} = 100 \mu\text{A}$
Drain current	I _{D(op)}	10	15	20	mA	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}$ $V_{G2S} = 4 \text{ V}, R_G = 220 \text{ k}\Omega$
Forward transfer admittance	y _{fs}	16	22	_	mS	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}$ $V_{G2S} = 4 \text{ V}$ $R_G = 220 \text{ k}\Omega, f = 1 \text{ kHz}$
Input capacitance	Ciss	1.2	1.7	2.2	pF	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}$
Output capacitance	Coss	0.7	1.1	1.5	pF	$V_{G2S} = 4 \text{ V}, R_{G} = 220 \text{ k}\Omega$
Reverse transfer capacitance	Crss	_	0.012	0.03	pF	f = 1 MHz
Power gain	PG	16	20	_	dB	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}$ $V_{G2S} = 4 \text{ V}$
Noise figure	NF		2.0	3.0	dB	$R_G = 220 \text{ k}\Omega, f = 900 \text{ MHz}$

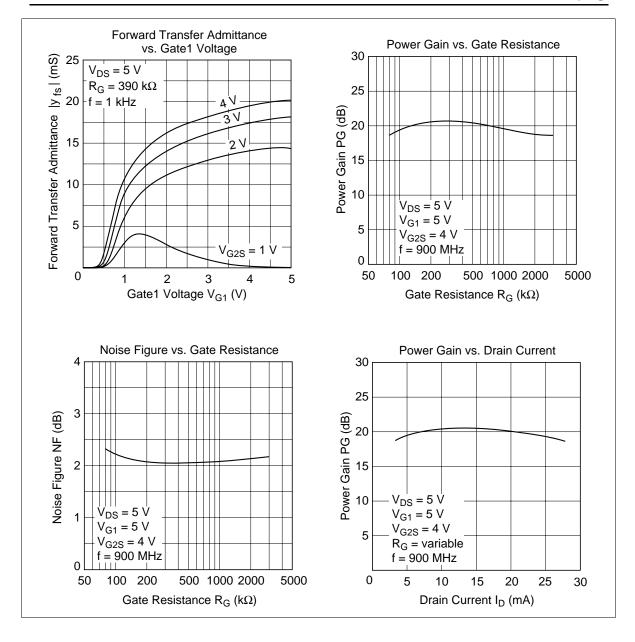
Note: Marking is "AU-".

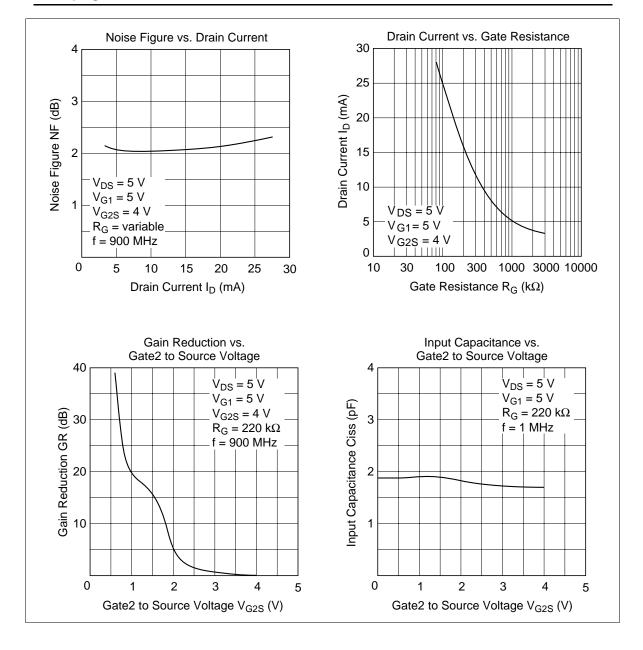
Main Characteristics

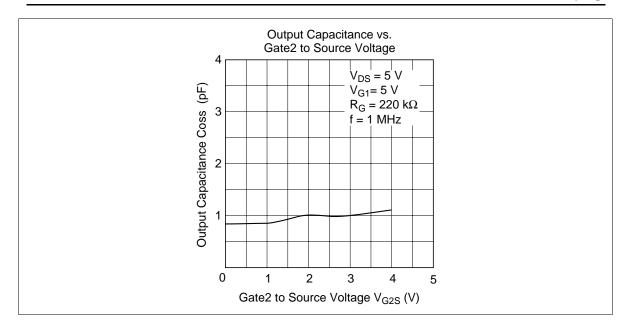






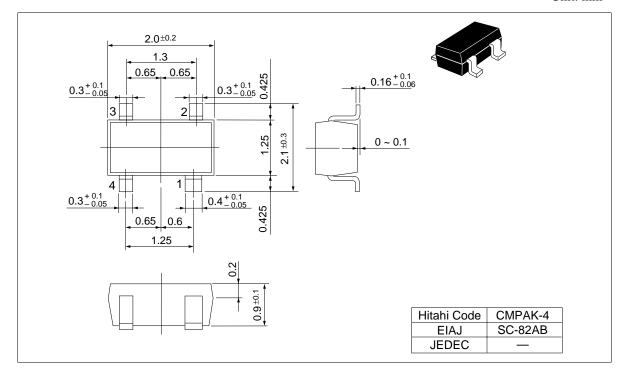






Package Dimentions

Unit: mm



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